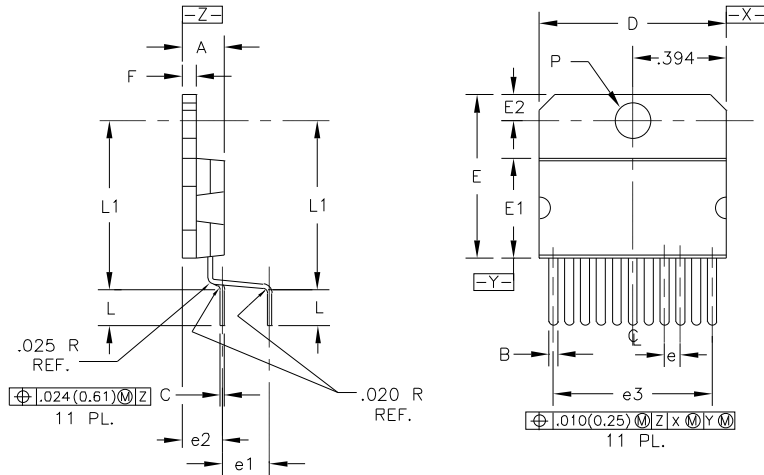


Package Number 242 - 11-Pin Plastic ZIP



| DIM | INCHES | | MILLIMETERS | | NOTE | DIM | INCHES | | MILLIMETERS | | NOTE |
|-----|--------|-------|-------------|-------|------|-----|--------|------|-------------|------|------|
| | MIN. | MAX. | MIN. | MAX. | | | MIN. | MAX. | MIN. | MAX. | |
| A | .172 | .182 | 4.37 | 4.62 | | N | .11 | .11 | 2.79 | 2.79 | 3 |
| B | .035 | .041 | 0.89 | 1.04 | | P | .148 | .152 | 3.76 | 3.86 | |
| C | .014 | .024 | 0.36 | 0.61 | | R1 | .065 | .080 | 1.65 | 2.03 | |
| D | .778 | .798 | 19.76 | 20.27 | | | | | | | |
| E | .684 | .694 | 17.37 | 17.63 | | | | | | | |
| E1 | .416 | .426 | 10.57 | 10.82 | | | | | | | |
| E2 | .110 | BASIC | .279 | BASIC | | | | | | | |
| e | .067 | BASIC | 1.70 | BASIC | | | | | | | |
| e1 | .200 | BASIC | 5.08 | BASIC | | | | | | | |
| e2 | .169 | BASIC | 4.29 | BASIC | | | | | | | |
| e3 | .670 | BASIC | 17.02 | BASIC | | | | | | | |
| F | .057 | .063 | 1.45 | 1.60 | | | | | | | |
| L | .150 | .176 | 3.81 | 4.47 | | | | | | | |
| L1 | .690 | .710 | 17.53 | 18.03 | | | | | | | |

NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5-1982.
2. CONTROLLING DIMENSION: INCH.
3. N IS THE MAXIMUM QUANTITY OF LEAD POSITIONS.

PACKAGE NUMBER: ZZ242 REV.: C
 JEDEC NUMBER: MO-48 (AA)



PACKAGE DRAWING

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